

## Voltage Protection for 2-Series, 3-Series, or 4-Series Cell Li-Ion Batteries (Second-Level Protection)

Check for Samples: [bq29440](#), [bq2944L0](#), [bq29441](#), [bq29442](#), [bq29443](#), [bq29449](#), [bq2944L9](#)

### FEATURES

- 2-Series, 3-Series, or 4-Series Cell Secondary Protection
- External Capacitor-Controlled Delay Timer
- Low Power Consumption  $I_{CC} < 2 \mu A$  Typical [ $V_{CELL(ALL)} < V_{PROTECT}$ ]
- High-Accuracy Overvoltage Protection:  $\pm 25$  mV with  $T_A = 0^\circ C$  to  $60^\circ C$
- Fixed Overvoltage Protection Thresholds: 4.30 V, 4.35 V, 4.40 V, 4.45 V, 4.50 V
- Small 8L QFN Package

### APPLICATIONS

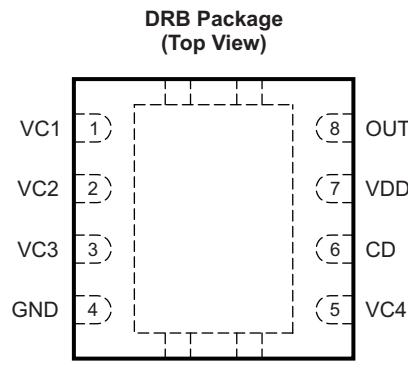
- Second-Level Protection in Li-Ion Battery Packs
  - Notebook Computers
  - Power Tools
  - Portable Equipment and Instrumentation

### DESCRIPTION

The bq2944x is a secondary overvoltage protection IC for 2-series, 3-series, or 4-series cell Li-Ion battery packs that incorporates a high-accuracy precision overvoltage detection circuit.

### FUNCTION

The voltage of each cell in a battery pack is compared to an internal reference voltage. If any cells reach an overvoltage condition, the bq2944x device starts a timer that provides a delay proportional to the capacitance on the CD pin. Upon expiration of the internal timer, the OUT pin changes from a low state to a high state. An optional latch configuration is available that holds the OUT pin in a high state indefinitely after an overvoltage condition has satisfied the specified delay timer period. The latch is released when the CD pin is shorted to GND.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Table 1. ORDERING INFORMATION<sup>(1)</sup>

T <sub>A</sub>	PART NUMBER	OUT PIN LATCH OPTION	PACKAGE	PACKAGE DESIGNATOR	PACKAGE MARKING	OVP	ORDERING INFORMATION <sup>(2)</sup>	
							TAPE AND REEL (LARGE) <sup>(3)</sup>	TAPE AND REEL (SMALL) <sup>(4)</sup>
-40°C to +110°C	BQ29440	No	QFN-8	DRB	440	4.35 V	BQ29440DRBR	BQ29440DRBT
	BQ2944L0	Yes			44L0	4.35 V	BQ2944L0DRBR	BQ2944L0DRBT
	BQ29441	No			441	4.40 V	BQ29441DRBR	BQ29441DRBT
	BQ29442	No			442	4.45 V	BQ29442DRBR	BQ29442DRBT
	BQ29443	No			443	4.50 V	BQ29443DRBR	BQ29443DRBT
	BQ29449	No			449	4.30 V	BQ29449DRBR	BQ29449DRBT
	BQ2944L9	Yes			44L9	4.30 V	BQ2944L9DRBR	BQ2944L9DRBT

(1) Example: bq2944L0DRBR is a device with the OUT latch option with a  $V_{OV}$  threshold of 4.35 V.

Contact Texas Instruments for other  $V_{OV}$  threshold options.

(2) For the most current package and ordering information, see the Package Addendum at the end of this document, or the TI website at [www.ti.com](http://www.ti.com).

(3) Large tape and reel quantity is 3,000 units.

(4) Small tape and reel quantity is 250 units.

## THERMAL INFORMATION

THERMAL METRIC <sup>(1)</sup>		bq2944x	UNITS
		DRB	
		8 PINS	
$\theta_{JA}$	Junction-to-ambient thermal resistance <sup>(2)</sup>	50.5	°C/W
$\theta_{JC(\text{top})}$	Junction-to-case(top) thermal resistance <sup>(3)</sup>	25.1	
$\theta_{JB}$	Junction-to-board thermal resistance <sup>(4)</sup>	19.3	
$\psi_{JT}$	Junction-to-top characterization parameter <sup>(5)</sup>	0.7	
$\psi_{JB}$	Junction-to-board characterization parameter <sup>(6)</sup>	18.9	
$\theta_{JC(\text{bottom})}$	Junction-to-case(bottom) thermal resistance <sup>(7)</sup>	5.2	

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](#).

(2) The junction-to-ambient thermal resistance under natural convection is obtained in a simulation on a JEDEC-standard, high-K board, as specified in JESD51-7, in an environment described in JESD51-2a.

(3) The junction-to-case (top) thermal resistance is obtained by simulating a cold plate test on the package top. No specific JEDEC-standard test exists, but a close description can be found in the ANSI SEMI standard G30-88.

(4) The junction-to-board thermal resistance is obtained by simulating in an environment with a ring cold plate fixture to control the PCB temperature, as described in JESD51-8.

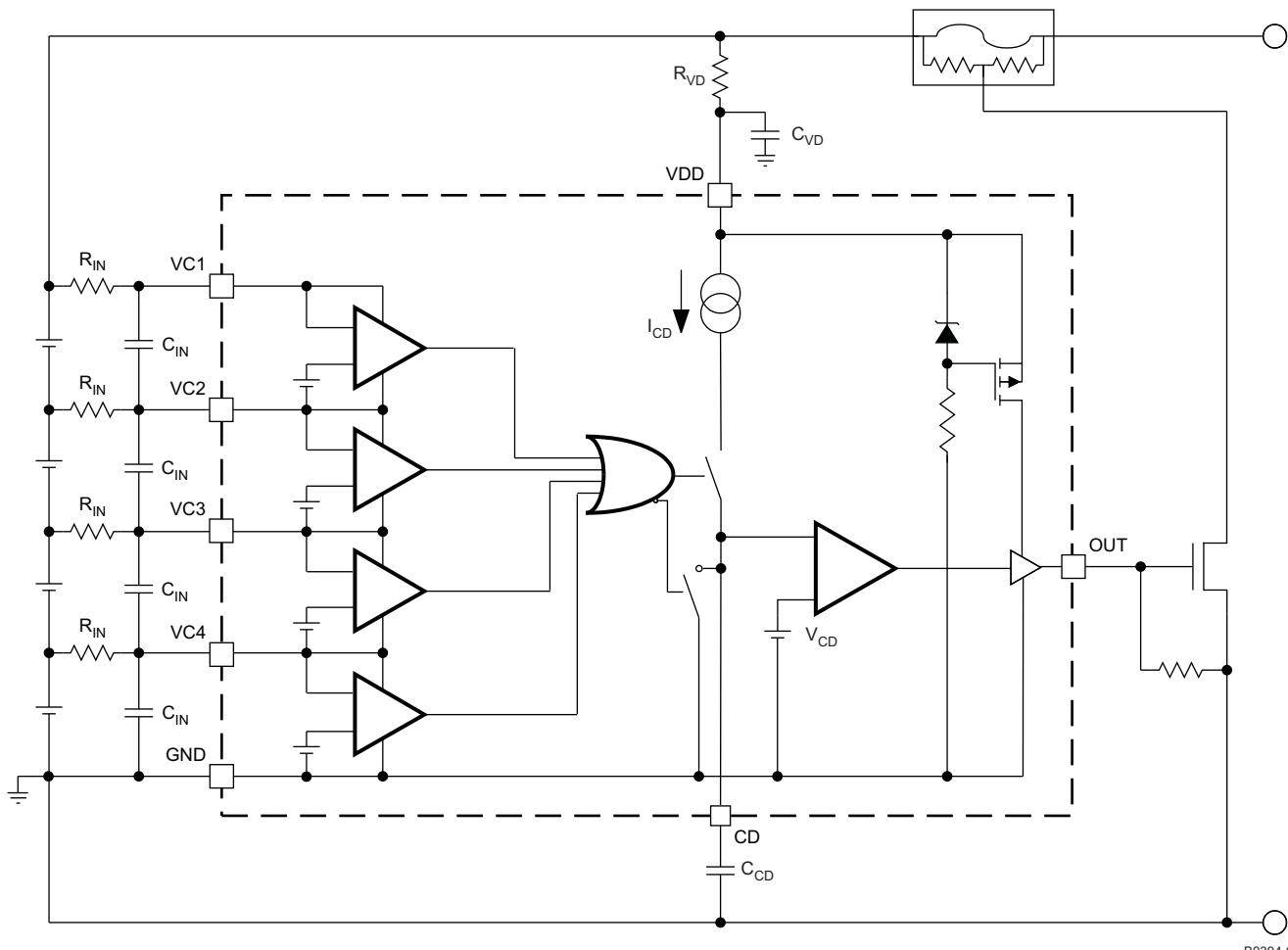
(5) The junction-to-top characterization parameter,  $\psi_{JT}$ , estimates the junction temperature of a device in a real system and is extracted from the simulation data for obtaining  $\theta_{JA}$ , using a procedure described in JESD51-2a (sections 6 and 7).

(6) The junction-to-board characterization parameter,  $\psi_{JB}$ , estimates the junction temperature of a device in a real system and is extracted from the simulation data for obtaining  $\theta_{JA}$ , using a procedure described in JESD51-2a (sections 6 and 7).

(7) The junction-to-case (bottom) thermal resistance is obtained by simulating a cold plate test on the exposed (power) pad. No specific JEDEC standard test exists, but a close description can be found in the ANSI SEMI standard G30-88.

## PIN FUNCTIONS

PIN NAME	PIN NO.	DESCRIPTION
CD	6	Connection to external capacitor for programmable delay time
GND	4	Ground pin
OUT	8	Output
VC1	1	Sense voltage input for top cell
VC2	2	Sense voltage input for second-to-top cell
VC3	3	Sense voltage input for third-to-top cell
VC4	5	Sense voltage input for fourth-to-top cell (bottom cell)
VDD	7	Power supply

**FUNCTIONAL BLOCK DIAGRAM**

**ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>**

over operating free-air temperature range (unless otherwise noted)

		VALUE/UNIT
Supply voltage range, $V_{MAX}$	VDD–GND	–0.3 to 28 V
	VC1–GND, VC2–GND, VC3–GND	–0.3 to 28 V
Input voltage range, $V_{IN}$	VC1–VC2, VC2–VC3, VC3–VC4, VC4–GND	–0.3 to 8 V
	CD–GND	–0.3 to 8 V
Output voltage range, $V_{OUT}$	OUT–GND	–0.3 to 28 V
Storage temperature range, $T_{stg}$		–65°C to 150°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

**RECOMMENDED OPERATING CONDITIONS**

		MIN	NOM	MAX	UNIT
Supply voltage, VDD		4	25		V
Input voltage range	VC1–VC2, VC2–VC3, VC3–VC4, VC4–GND	0	5		V
$t_{d(CD)}$ delay-time capacitance	$C_{CD}$ (See <a href="#">Figure 7</a> .)		0.1		$\mu F$
Voltage monitor filter resistance	$R_{IN}$ (See <a href="#">Figure 7</a> .)	0.1	1		$k\Omega$

## RECOMMENDED OPERATING CONDITIONS (continued)

		MIN	NOM	MAX	UNIT
Voltage monitor filter capacitance	$C_{IN}$ (See Figure 7.)	0.01	0.1		$\mu F$
Supply voltage filter resistance	$R_{VD}$ (See Figure 7.)	0.1		1	$k\Omega$
Supply voltage filter capacitance	$C_{VD}$ (See Figure 7.)		0.1		$\mu F$
Operating ambient temperature range, $T_A$		–40		110	$^{\circ}C$

## ELECTRICAL CHARACTERISTICS

Typical values stated where  $T_A = 25^{\circ}C$  and  $VDD = 17 V$ , MIN/MAX values stated where  $T_A = -40^{\circ}C$  to  $110^{\circ}C$  and  $VDD = 4 V$  to  $25 V$  (unless otherwise noted).

PARAMETER	TEST CONDITION	MIN	NOM	MAX	UNIT
$V_{PROTECT}$	bq29440		4.35		V
	bq29441		4.40		
	bq29442		4.45		
	bq29443		4.50		
	bq29449		4.30		
$V_{HYS}$	Overvoltage detection hysteresis	200	300	400	mV
$V_{OA}$	Overvoltage detection accuracy	$T_A = 25^{\circ}C$	–10	10	mV
$V_{OA\_DRIFT}$	Overvoltage threshold temperature drift	$T_A = 0^{\circ}C$ to $60^{\circ}C$	–0.4	0.4	mV/ $^{\circ}C$
		$T_A = -40^{\circ}C$ to $110^{\circ}C$	–0.6	0.6	
$X_{DELAY}$	Overvoltage delay time scale factor	$T_A = 0^{\circ}C$ to $60^{\circ}C$ Note: Does not include external capacitor variation	6.0	9.0	12
		$T_A = -40^{\circ}C$ to $110^{\circ}C$ Note: Does not include external capacitor variation	5.5	9.0	13.5
$X_{DELAY\_CTM}$	Overvoltage delay time scale factor in Customer Test Mode	See CUSTOMER TEST MODE.		0.08	s/ $\mu F$
$I_{CD(CHG)}$	Overvoltage detection charging current	See Figure 1.		140	nA
$I_{CD(DSG)}$	Overvoltage detection discharging current	See Figure 2.		60	$\mu A$
$V_{CD}$	Overvoltage detection external capacitor comparator threshold			1.2	V
$I_{CC}$	Supply current	(VC1–VC2), (VC2–VC3), (VC3–VC4) and (VC4–GND) = 3.5 V See Figure 3.		2	$\mu A$
$V_{OUT}$	OUT pin drive voltage	(VC1–VC2), (VC2–VC3), (VC3–VC4) or (VC4–GND) = $V_{PROTECT}$ , $VDD = 20 V$ , $I_{OH} = 0$ to $-10 \mu A$	6.5	8.0	9.5
		(VC1–VC2), (VC2–VC3), (VC3–VC4) or (VC4–GND) = $V_{PROTECT}$ , $VDD = 4.35 V$ , $I_{OL} = -10 \mu A$ , $T_A = 0^{\circ}C$ to $60^{\circ}C$	1.50	3.0	V
		(VC1–VC2), (VC2–VC3), (VC3–VC4) or (VC4–GND) = $V_{PROTECT}$ , $VDD > 6 V$ , $I_{OH} = -10 \mu A$ , $T_A = 0^{\circ}C$ to $60^{\circ}C$	2.0	3.0	V
		(VC1–VC2), (VC2–VC3), (VC3–VC4) or (VC4–GND) = 4 V, $I_{OL} = 0 \mu A$		0.1	V
$I_{OUT(SHORT)}$	OUT short circuit current	OUT = 0 V, (VC1–VC2), (VC2–VC3), (VC3–VC4) or (VC4–GND) > $V_{PROTECT}$ , $VDD = 18 V$		4	mA
$t_{r(OUT)}^{(1)}$	OUT output rise time	$C_L = 1 nF$ , $VDD = 4 V$ to $25 V$ , $V_{OH(OUT)} = 0 V$ to $5 V$		5	$\mu s$
$Z_{O(OUT)}^{(1)}$	OUT output impedance			2	$k\Omega$

(1) Specified by design. Not 100% tested in production.

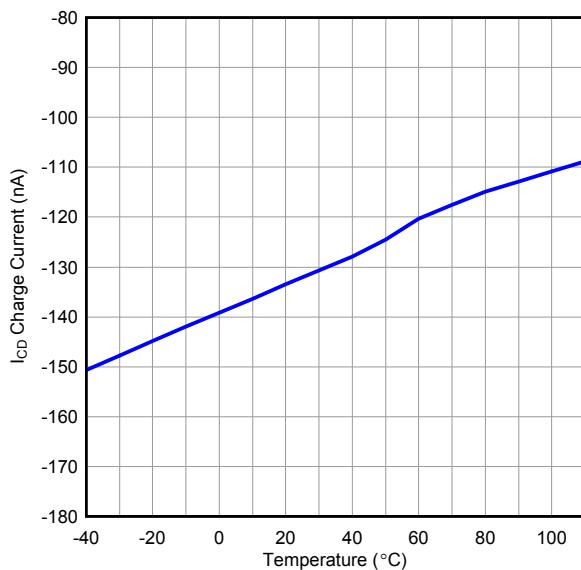
## ELECTRICAL CHARACTERISTICS (continued)

Typical values stated where  $T_A = 25^\circ\text{C}$  and  $\text{VDD} = 17\text{ V}$ , MIN/MAX values stated where  $T_A = -40^\circ\text{C}$  to  $110^\circ\text{C}$  and  $\text{VDD} = 4\text{ V}$  to  $25\text{ V}$  (unless otherwise noted).

PARAMETER	TEST CONDITION	MIN	NOM	MAX	UNIT
$I_{IN}$ Input current at $VCx$ pins	Measured at $VC1$ , $(VC1-VC2)$ , $(VC2-VC3)$ , $(VC3-VC4)$ and $(VC4-GND) = 3.5\text{ V}$ , $T_A = 0^\circ\text{C}$ to $60^\circ\text{C}$ See Figure 3.	-0.3		1.5	$\mu\text{A}$
	Measured at $VC2$ , $VC3$ OR $VC4$ , $(VC1-VC2)$ , $(VC2-VC3)$ , $(VC3-VC4)$ and $(VC4-GND) = 3.5\text{ V}$ , $T_A = 0^\circ\text{C}$ to $60^\circ\text{C}$ See Figure 3.	-0.3		0.3	$\mu\text{A}$

## TYPICAL CHARACTERISTICS

$I_{CD}$  CHARGE CURRENT  
vs  
TEMPERATURE



$I_{CD}$  DISCHARGE CURRENT  
vs  
TEMPERATURE

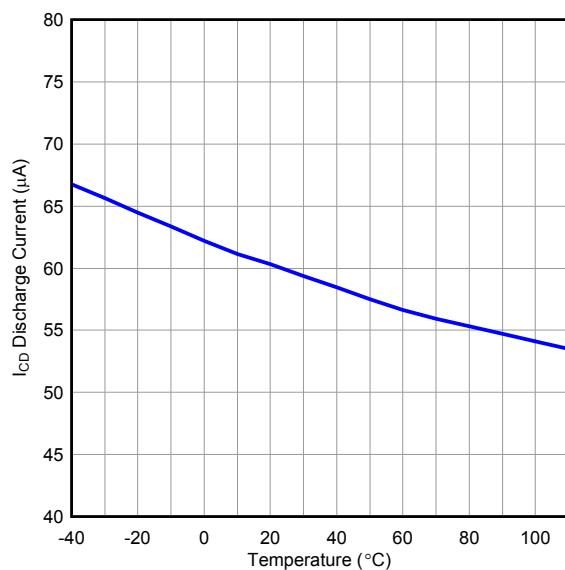


Figure 1.  $I_{CD}$  Charge Current

Figure 2.  $I_{CD}$  Discharge Current

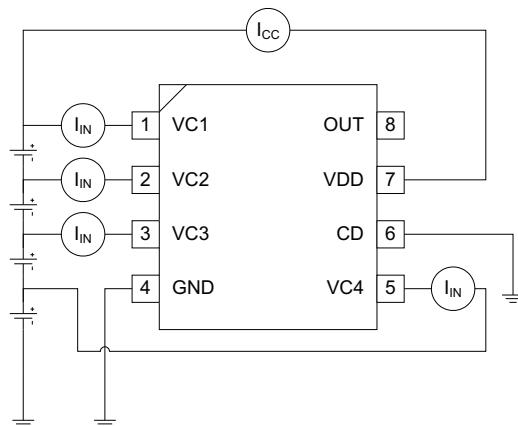
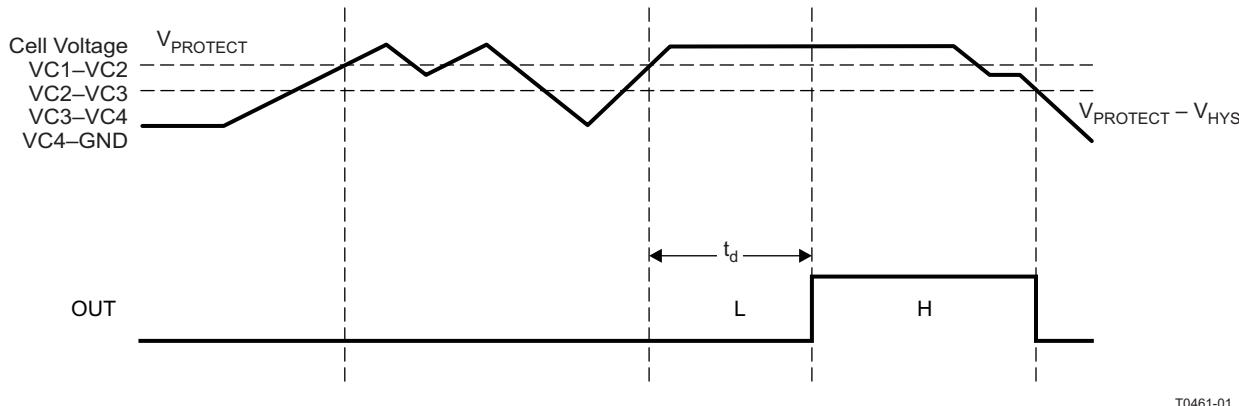


Figure 3.  $I_{CC}$ ,  $I_{IN}$  Measurement

## APPLICATIONS INFORMATION

### PROTECTION (OUT) TIMING AND DELAY TIME CAPACITOR SIZING

The bq2944x uses an external capacitor to set delay timing during an overvoltage condition. When any of the cells exceed the overvoltage threshold, the bq2944x activates an internal current source of nominally 140 nA, which charges the external capacitor. When the external capacitor charges up to a voltage of nominally 1.2 V, the OUT pin transitions from a low state to a high state, by means of an internal pull-up network, to a regulated voltage of no more than 9.5 V when  $I_{OH} = 0$  mA.



T0461-01

Figure 4. Timing for Overvoltage Sensing

Sizing the external capacitor is based on the desired delay time as follows:

$$C_{CD} = \frac{t_d}{X_{DELAY}}$$

Where  $t_d$  is the desired delay time and  $X_{DELAY}$  is the overvoltage delay time scale factor, expressed in seconds per microFarad.  $X_{DELAY}$  is nominally 9.0 s/ $\mu$ F. For example, if a nominal delay of 3 seconds is desired, the customer should use a  $C_{CD}$  capacitor that is  $3\text{ s}/9.0\text{ s}/\mu\text{F} = 0.33\text{ }\mu\text{F}$ .

The delay time is calculated as follows:

$$t_d = C_{CD} \times X_{DELAY}$$

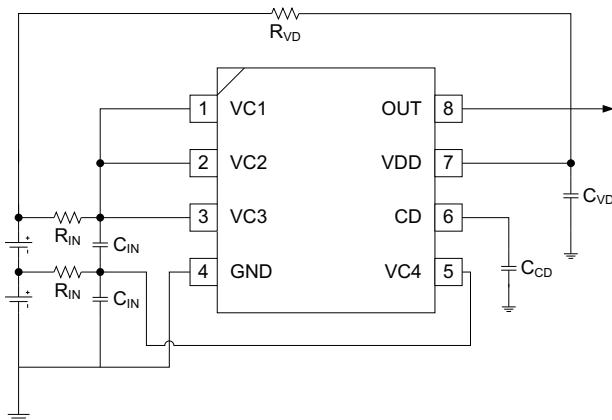
If the cell overvoltage condition is removed before the external capacitor reaches the reference voltage, the internal current source is disabled and an internal discharge block is employed to discharge the external capacitor down to 0 V. In this instance, the OUT pin remains in a low state.

For latched versions of the bq2944x, if an overvoltage condition has caused the OUT pin to transition to a high state, the external capacitor remains charged even after the overvoltage condition has been removed. In this instance, the OUT pin remains in a high state.

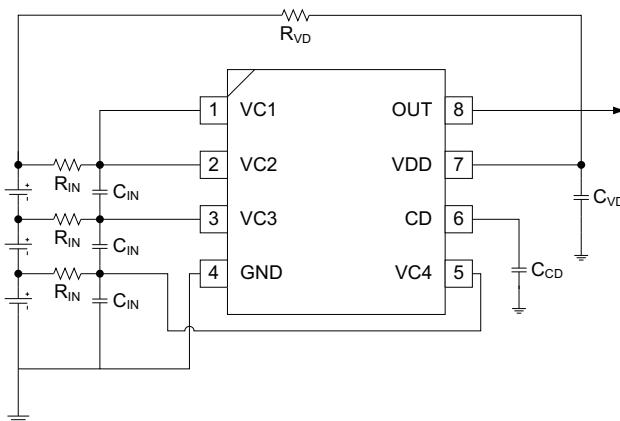
For non-latched versions, the OUT pin is allowed to transition back from a high to low state when the overvoltage condition is no longer present, and the external capacitor is discharged down to 0 V.

## BATTERY CONNECTION FOR 2-SERIES, 3-SERIES, AND 4-SERIES CELL CONFIGURATIONS

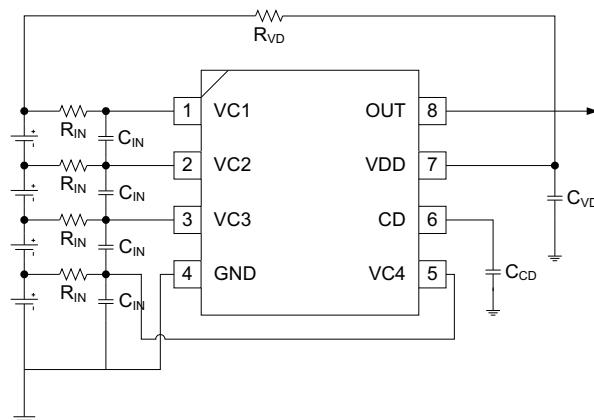
Figure 5, Figure 6, and Figure 7 show the 2-series, 3-series, and 4-series cell configurations.



**Figure 5. 2-Series Cell Configuration**



**Figure 6. 3-Series Cell Configuration**



**Figure 7. 4-Series Cell Configuration**

## CELL CONNECTION SEQUENCE

### NOTE

Before connecting the cells, propagate the overvoltage delay timing capacitor,  $C_{CD}$ .

The recommended cell connection sequence begins from the bottom of the stack, as follows:

1. GND
2. VC4
3. VC3
4. VC2
5. VC1

While not advised, connecting the cells in a sequence other than that described above does not result in errant activity on the OUT pin. For example:

1. GND
2. VC4, VC3, VC2, or VC1
3. Remaining VCx pin
4. Remaining VCx pin
5. Remaining VCx pin

## CUSTOMER TEST MODE

Customer Test Mode (CTM) helps to greatly reduce the overvoltage detection delay time and enable quicker customer production testing. This mode is intended for quick-pass board-level verification tests, and, as such, individual cell overvoltage levels may deviate slightly from the specifications ( $V_{PROTECT}$ ,  $V_{OA}$ ). If accurate overvoltage thresholds are to be tested, use the standard delay settings that are intended for normal use.

To enter CTM, VDD should be set to approximately 9.5 V higher than VC1. When CTM is entered, the device switches from the normal overvoltage delay time scale factor,  $x_{DELAY}$ , to a significantly reduced factor,  $x_{DELAY\_CTM}$ , thereby reducing the delay time during an overvoltage condition. The CTM overvoltage delay time is similar to the equation presented in [PROTECTION \(OUT\) TIMING AND DELAY TIME CAPACITOR SIZING](#) with the substitution of  $x_{DELAY\_CTM}$  in place of  $x_{DELAY}$ :

$$t_d_{CTM} = C_{CD} \times X_{DELAY\_CTM}$$

### CAUTION

Avoid exceeding any Absolute Maximum Voltages on any pins when placing the part into Customer Test Mode. Also, avoid exceeding Absolute Maximum Voltages for the individual cell voltages (VC1–VC2), (VC2–VC3), (VC3–VC4), and (VC4–GND). Stressing the pins beyond the rated limits may cause permanent damage to the device.

To exit CTM, power off the device and then power it back on.

For latched versions of the bq2944x, the external  $C_{CD}$  capacitor must be externally discharged if any overvoltage functionality is exercised during protection testing. This can be accomplished by shorting the CD pin to GND. If the  $C_{CD}$  capacitor is not explicitly discharged, a residual charge may cause the overvoltage delay time to be inaccurate.

## REVISION HISTORY

Changes from Revision B (June 2010) to Revision C	Page
• Added new protection thresholds .....	1
• Changed occurrences of $V_{DD}$ to VDD throughout document .....	1
• Added part numbers .....	2
• Changed the Functional Block Diagram .....	3
• Changed the Electrical Characteristics .....	4
• Deleted 3.5 from one of the maximum values from the $V_{OUT}$ specification .....	4
• Changed nominal delay time .....	6

## PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
BQ29440DRBR	NRND	SON	DRB	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	440	
BQ29440DRBT	NRND	SON	DRB	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	440	
BQ29441DRBR	NRND	SON	DRB	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	441	
BQ29441DRBT	NRND	SON	DRB	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	441	
BQ29442DRBR	NRND	SON	DRB	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	442	
BQ29442DRBT	NRND	SON	DRB	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	442	
BQ29443DRBR	NRND	SON	DRB	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	443	
BQ29443DRBT	NRND	SON	DRB	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	443	
BQ29449DRBR	NRND	SON	DRB	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	449	
BQ29449DRBT	NRND	SON	DRB	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	449	

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

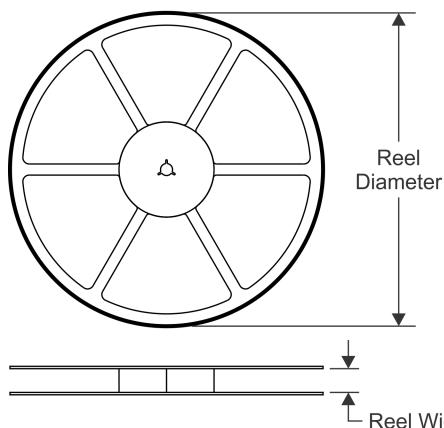
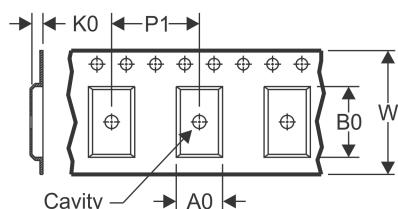
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

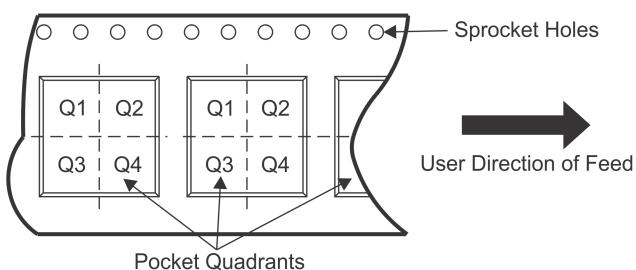
(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
BQ29440DRBR	SON	DRB	8	3000	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
BQ29440DRBT	SON	DRB	8	250	180.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
BQ29441DRBR	SON	DRB	8	3000	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
BQ29441DRBT	SON	DRB	8	250	180.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
BQ29442DRBR	SON	DRB	8	3000	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
BQ29442DRBT	SON	DRB	8	250	180.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
BQ29443DRBR	SON	DRB	8	3000	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
BQ29443DRBT	SON	DRB	8	250	180.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
BQ29449DRBR	SON	DRB	8	3000	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
BQ29449DRBT	SON	DRB	8	250	180.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2

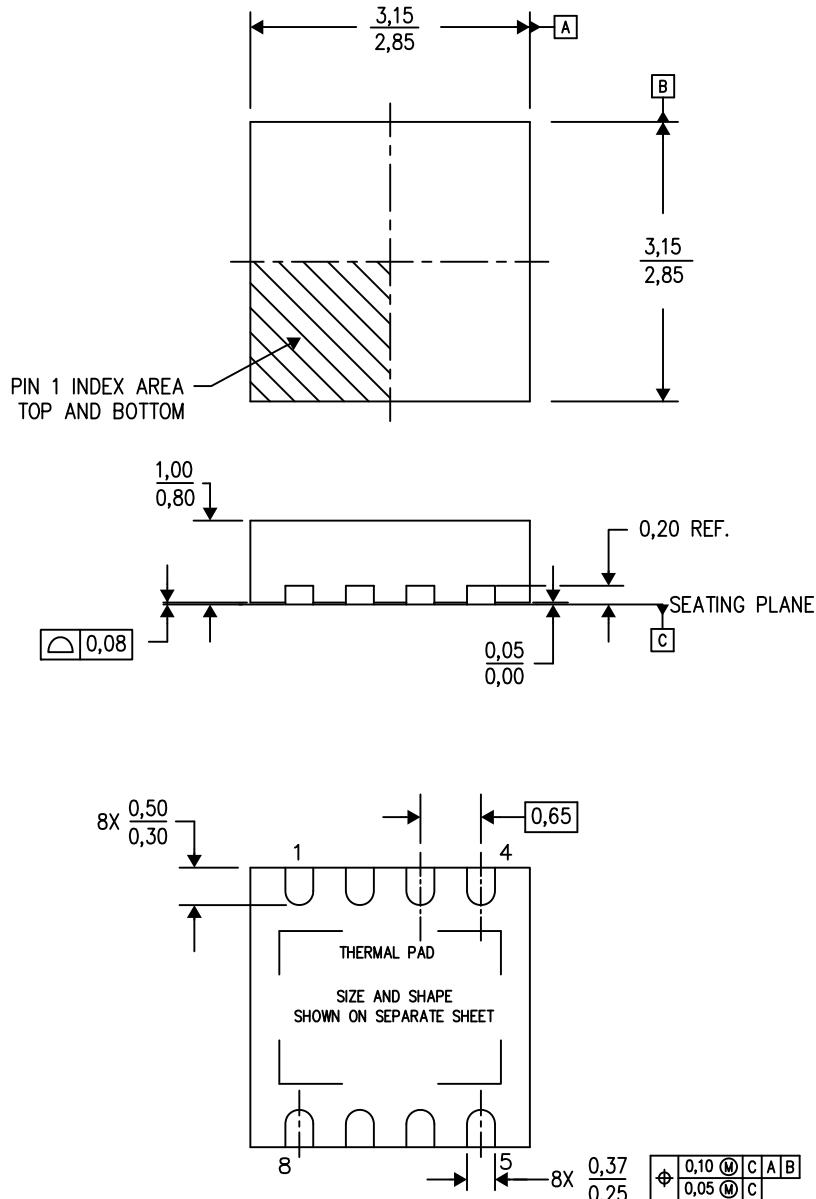
**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
BQ29440DRBR	SON	DRB	8	3000	367.0	367.0	35.0
BQ29440DRBT	SON	DRB	8	250	210.0	185.0	35.0
BQ29441DRBR	SON	DRB	8	3000	367.0	367.0	35.0
BQ29441DRBT	SON	DRB	8	250	210.0	185.0	35.0
BQ29442DRBR	SON	DRB	8	3000	367.0	367.0	35.0
BQ29442DRBT	SON	DRB	8	250	210.0	185.0	35.0
BQ29443DRBR	SON	DRB	8	3000	367.0	367.0	35.0
BQ29443DRBT	SON	DRB	8	250	210.0	185.0	35.0
BQ29444DRBR	SON	DRB	8	3000	367.0	367.0	35.0
BQ29444DRBT	SON	DRB	8	250	210.0	185.0	35.0

DRB (S-PVSON-N8)

PLASTIC SMALL OUTLINE NO-LEAD



Bottom View

4203482-2/K 06/12

NOTES:

- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
- This drawing is subject to change without notice.
- Small Outline No-Lead (SON) package configuration.
- The package thermal pad must be soldered to the board for thermal and mechanical performance.
- See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.

# THERMAL PAD MECHANICAL DATA

DRB (S-PVSON-N8)

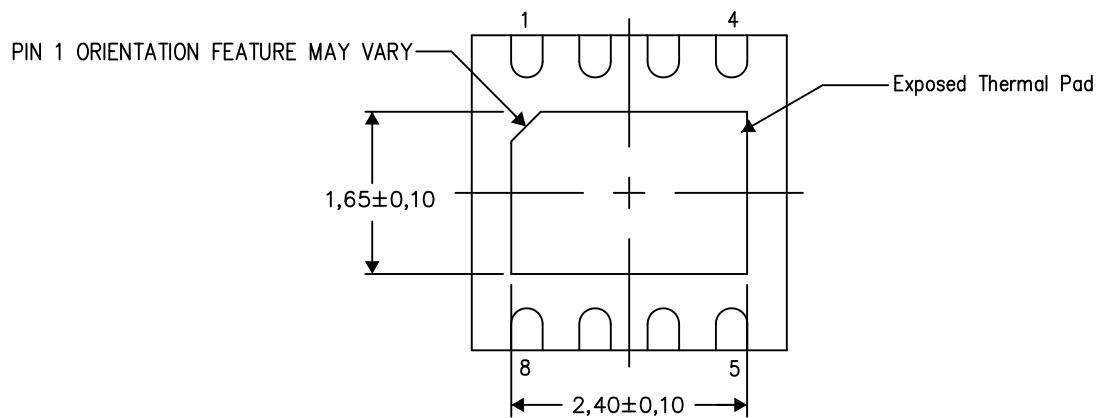
PLASTIC SMALL OUTLINE NO-LEAD

## THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at [www.ti.com](http://www.ti.com).

The exposed thermal pad dimensions for this package are shown in the following illustration.



Bottom View

Exposed Thermal Pad Dimensions

4206340-3/N 09/12

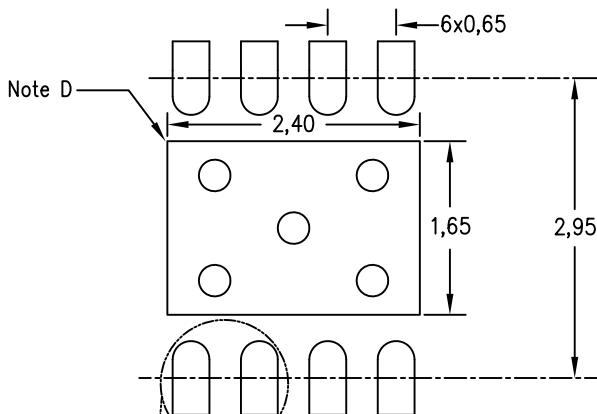
NOTE: All linear dimensions are in millimeters

# LAND PATTERN DATA

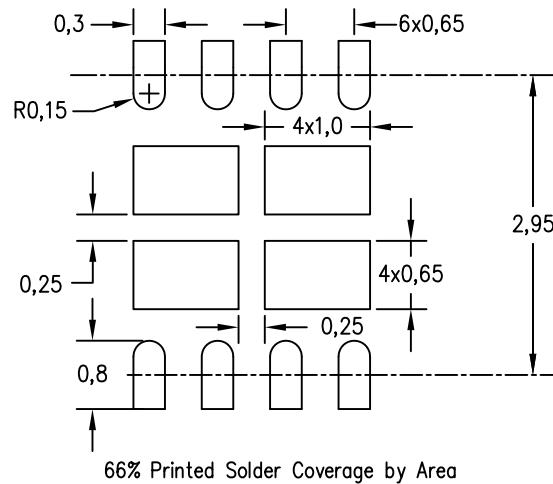
DRB (S-PVSON-N8)

PLASTIC SMALL OUTLINE NO-LEAD

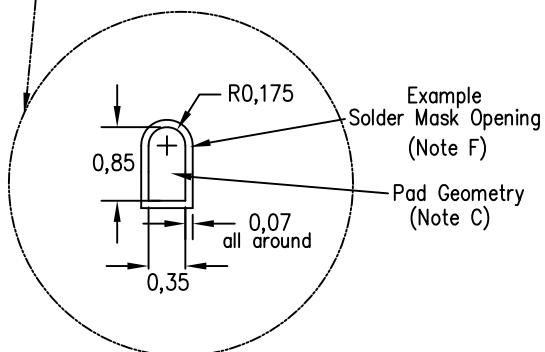
Example Board Layout



Example Stencil Design  
0,125mm Stencil Thickness  
(Note E)

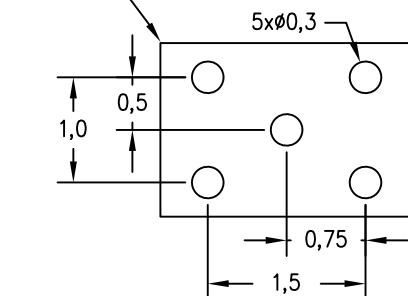


Non Solder Mask Defined Pad



Example Solder Mask Opening  
(Note F)

Center Pad Layout  
(Note D)



4207048-3/J 09/12

NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Publication IPC-7351 is recommended for alternate designs.
- This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, QFN Packages, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at [www.ti.com](http://www.ti.com) <<http://www.ti.com>>.
- Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
- Customers should contact their board fabrication site for solder mask tolerances.

## IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products	Applications
Audio	<a href="http://www.ti.com/audio">www.ti.com/audio</a>
Amplifiers	<a href="http://amplifier.ti.com">amplifier.ti.com</a>
Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>
DLP® Products	<a href="http://www.dlp.com">www.dlp.com</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>
Clocks and Timers	<a href="http://www.ti.com/clocks">www.ti.com/clocks</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>
RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>
OMAP Applications Processors	<a href="http://www.ti.com/omap">www.ti.com/omap</a>
Wireless Connectivity	<a href="http://www.ti.com/wirelessconnectivity">www.ti.com/wirelessconnectivity</a>
	<b>TI E2E Community</b>
	<a href="http://e2e.ti.com">e2e.ti.com</a>